















ESD

TVS

S I

LDO

Diode

Sensor

DC-DC

Product Specification

Domestic Part Number	EV-IRFR5410-T1
Overseas Part Number	IRFR5410
▶ Equivalent Part Number	IRFR5410

"T1" means TO-252





P-Ch 60V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Descript	ion
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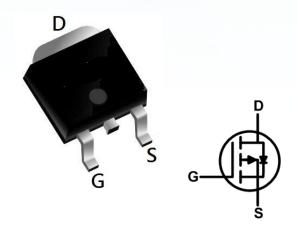
The EV-IRFR5410-T1 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The EV-IRFR5410-T1 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summary

BVDSS	RDSON	ID
-60V	90mΩ	-13A

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-60	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-13	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-8.3	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.3	А
I _D @T _A =70°C	©T _A =70°C Continuous Drain Current, V _{GS} @ -10V ¹ -2.7		А
I _{DM}	Pulsed Drain Current ²	-26	А
EAS	Single Pulse Avalanche Energy ³	29.8	mJ
I _{AS}	Avalanche Current	24.4	А
P _D @T _C =25°C	Total Power Dissipation ⁴	31.3	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		62	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		4	°C/W



P-Ch 60V Fast Switching MOSFETs

P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.023		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-10A			90	0
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-5A			115	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-1.0		-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS=VDS , ID =-250UA		4.65		mV/°C
	Drain Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =25°C			1	
IDSS	Drain-Source Leakage Current V _{DS} =-48V , V _{GS} =0V , T _J =55°C			5	uA uA	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V_{DS} =-5 V , I_{D} =-4 A		8.7		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		15		Ω
Q_{g}	Total Gate Charge (-4.5V)			11.8		
Q_gs	Gate-Source Charge	V _{DS} =-12V , V _{GS} =-4.5V , I _D =-6A		1.9		nC
Q_gd	Gate-Drain Charge			6.5		
T _{d(on)}	Turn-On Delay Time			8.8		
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		19.6		
T _{d(off)}	Turn-Off Delay Time	I _D =-1A		47.2		ns
T _f	Fall Time			9.6		
Ciss	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		1080		
C _{oss}	Output Capacitance			73		pF
C _{rss}	Reverse Transfer Capacitance			50		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	-V _G =V _D =0V , Force Current			-13	Α
I _{SM}	Pulsed Source Current ^{2,5}				-26	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1 mH, I_{AS} =-24.4 A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



P-Channel Typical Characteristics

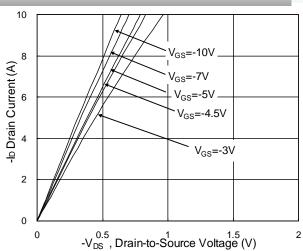


Fig.1 Typical Output Characteristics

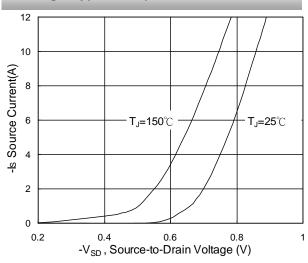


Fig.3 Forward Characteristics of Reverse

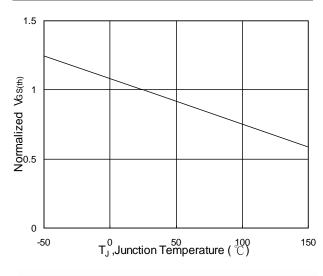


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

P-Ch 60V Fast Switching MOSFETs

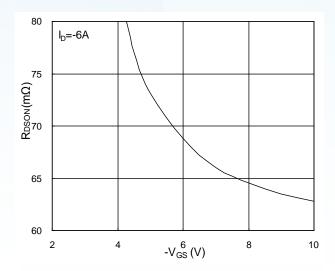


Fig.2 On-Resistance v.s Gate-Source

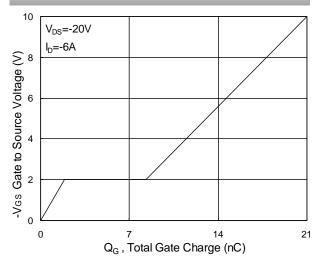


Fig.4 Gate-Charge Characteristics

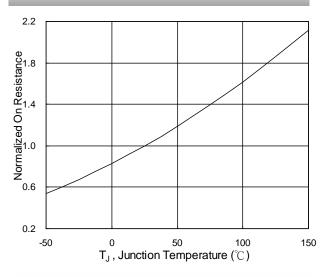
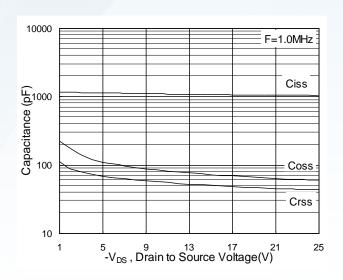


Fig.6 Normalized R_{DSON} v.s T_J



P-Ch 60V Fast Switching MOSFETs



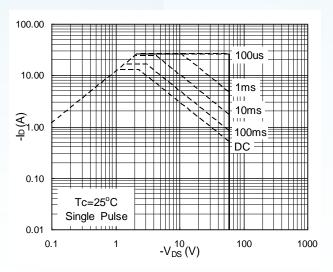


Fig.7 Capacitance

Fig.8 Safe Operating Area

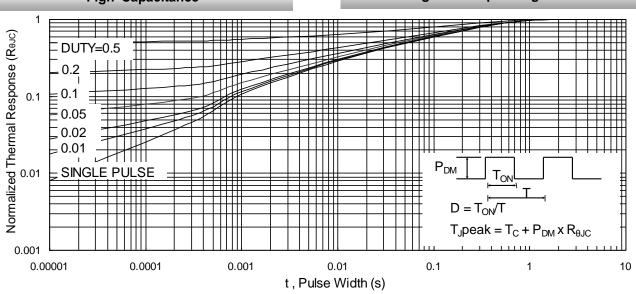


Fig.9 Normalized Maximum Transient Thermal Impedance

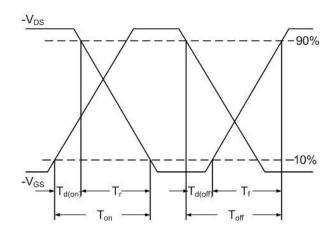


Fig.10 Switching Time Waveform

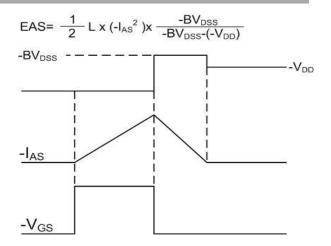


Fig.11 Unclamped Inductive Switching Waveform



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